

REMARKS

Applicant respectfully requests reconsideration of this application. Applicant submits the following response to overcome the Examiner's rejection. Claims 16-42 are still pending.

Declaration Under 37 C.F.R. § 1.131

In the Office Action, the Examiner has rejected claims 16, 17, 19, 24-27, 29, and 34-37 under 35 U.S.C. § 102(b) as being anticipated by Tokuno (U.S. Patent 5,892,289). The Examiner has also rejected claims 18, 20-23, 28, 30-33, and 39-42 under 35 U.S.C. § 103(a) as being unpatentable over Tokuno in view of Low et al. (U.S. Patent 5,886,398) and rejected claim 38 under 35 U.S.C. § 103(a) as being unpatentable over Tokuno in view of Woosley et al. (U.S. Patent 5,708,300). Applicant respectfully traverses the rejections.

Applicant herein submits a declaration under 37 CFR 1.131 under a separate cover to respond to the rejections. The effective date of the Tokuno reference is the United States filing date, which is April 22, 1997. Applicant respectfully submits that the 37 CFR 1.131 declaration of prior invention establishes invention of the subject matter of the rejected claims prior to the effective date of the Tokuno reference on which the 35 U.S.C. § 102(b) rejection and the 35 U.S.C. § 103(a) rejections are based.

The effective date of the Low et al. reference is the United States filing date, which is September 26, 1997. Applicant respectfully submits that the 37 CFR § 1.131 declaration of prior invention establishes invention of the subject matter of the rejected claims prior to the effective date of the Low et al. reference on which a 35 U.S.C. § 103(a) rejection is based.

Accordingly, Applicant respectfully requests the withdrawal of the 35 U.S.C. § 102(b)

rejection and the 35 U.S.C. § 103(a) rejections based on prior invention, as supported by the 37 C.F.R. § 1.131 declaration.

Rejections Under 35 U.S.C. § 102(b)

In the Office Action, the Examiner has rejected claims 16, 17, 19, 24-27, 29, and 34-37 under 35 U.S.C. §102(b) as being anticipated by Tokuno (U.S. Patent 5,892,289). Applicant respectfully traverses the rejection.

The present application is a divisional patent application of U.S. Patent Application No. 09/527,284, filed March 17, 2000, now pending, which is a divisional patent application of U.S. Patent Application No. 08/986,275, filed December 5, 1997, now U.S. Patent No. 6,064,117.

Because the earliest parent application of this divisional application was filed December 5, 1997 and therefore prior to the April 6, 1999 issue date of Tokuno, Applicant respectfully submits that the 102(b) rejection is not applicable in this case.

Applicant therefore respectfully submits that the §102(b) rejection should accordingly be withdrawn.

Although the declaration under 37 C.F.R. § 1.131 has been submitted to withdraw the § 102(b) rejection with respect to Tokuno, Applicant also presents the following argument to further refute the § 102 (b) rejection. Applicant respectfully submits Tokuno teaches, “at each of the corners of the semiconductor chip 1, at least two [resin] fillets 50 have a relatively larger size than the [resin] fillets 5 as formed along each side of the semiconductor chip 1 and accordingly, the corner portions 11 to 14 are reinforced...” (see Column 3, Lines 55-59 of Tokuno) In Tokuno, the resin fillets 50 reinforce the corner portions 11-14 of the semiconductor chip. Tokuno fails to teach reinforcing the

corners of the substrate with a mold cap having a plurality of extensions each extending into a respective corner section of the substrate.

Applicant respectfully submits that Tokuno fails to disclose the embodiments of the invention of claim 16 claiming a mold cap disposed over the substrate such that the mold cap at least partially covers the chip, the mold cap having an extension extending into a corner section of the substrate.

Applicant respectfully submits that Tokuno fails to disclose the embodiments of the invention of claim 24 claiming a mold cap disposed over the substrate such that the mold cap at least partially covers the chip, the mold cap having a plurality of extensions each extending into a respective corner section of the substrate.

Applicant respectfully submits that Tokuno fails to disclose the embodiments of the invention of claim 34 claiming a mold cap disposed over the substrate such that the mold cap at least partially covers the chip, the mold cap having an extension adjacent a corner section of the substrate.

Applicant respectfully submits that Tokuno fails to disclose the embodiments of the invention as claimed in independent claims 16, 24, and 36. Accordingly, Applicant respectfully submits that the pending claims overcome any 35 U.S.C. § 102 rejections.

Rejection Under 35 U.S.C. § 103(a)

In the Office Action, the Examiner rejected claims 18, 20-23, 28, 30-33, and 39-42 under 35 U.S.C. § 103(a) as being unpatentable over Tokuno in view of Low et al. (U.S. Patent 5,886,398) and rejected claim 38 under 35 U.S.C. § 103(a) as being unpatentable over Tokuno in view of Woosley et al. (U.S. Patent 5,708,300). Applicant respectfully traverses the rejections.

Applicant respectfully submits that the declaration under 37 C.F.R. § 1.131 is applicable as

well for the withdrawal of the § 103(a) rejections with respect to Tokuno and Low and to withdraw the § 103(a) rejections with respect to Tokuno and Woosley. Furthermore, Applicant respectfully submits that Tokuno fails to disclose the embodiments of the invention as claimed for the reasons stated above.

Accordingly, Applicant respectfully requests the withdrawal of the 35 U.S.C. § 103(a) rejections with respect to Tokuno and Low, as well with respect to Tokuno and Woosley.

Conclusion

In view of the foregoing remarks, Applicant respectfully submits that all rejections as applied to the claims have been overcome and consequently that all claims as they currently stand are in condition for allowance. Applicant respectfully requests that all rejections be withdrawn and that the claims be allowed to issue.

Accordingly, Applicant respectfully submits that claims 16-42 are in condition for allowance and Applicant respectfully requests the allowance of these claims.

Please charge any insufficiency or credit any overpayment to Deposit Account No. 02-2666.

Respectfully submitted,

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

No claims have been canceled, amended, or added.